

NB4L6254

2.5V / 3.3V Differential LVPECL 2x2 Clock Switch and Low Skew Fanout Buffer



ON Semiconductor®

<http://onsemi.com>

Description

The NB4L6254 is a differential 2x2 clock switch and drives precisely aligned clock signals through its LVPECL fanout buffers. It employs a fully differential architecture with bipolar technology, offers superior digital signal characteristics, has very low clock output skew and supports clock frequencies from DC up to 3.0 GHz.

The NB4L6254 is designed for the most demanding, skew critical differential clock distribution systems. Typical applications for the NB4L6254 are clock distribution, switching and data loopback systems of high-performance computer, networking and telecommunication systems, as well as on-board clocking of OC-3, OC-12 and OC-48 communication systems. In addition, the NB4L6254 can be configured as a single 1:6 or dual 1:3 LVPECL fanout buffer.

The NB4L6254 can be operated from a single 3.3 V or 2.5 V power supply.

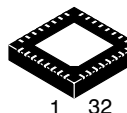
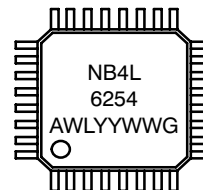
Features

- Maximum Clock Input Frequency, 3 GHz
- Maximum Input Data Rate, 3 Gb/s
- Differential LVPECL Inputs and Outputs
- Low Output Skew: 50 ps Maximum Output-to-Output Skew
- Synchronous Output Enable Eliminating Output Runt Pulse Generation and Metastability
- Operating Range: Single 3.3 V or 2.5 V Supply
 $V_{CC} = 2.375 \text{ V to } 3.465 \text{ V}$
- LVCMOS Compatible Control Inputs
- Packaged in LQFP-32
- Fully Differential Architecture
- -40 °C to 85 °C Ambient Operating Temperature
- These are Pb-Free Devices*

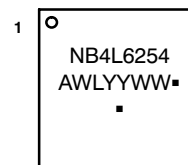
MARKING DIAGRAMS*



LQFP-32
FA SUFFIX
CASE 873A



QFN32
MN SUFFIX
CASE 488AM



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G or • = Pb-Free Package
(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

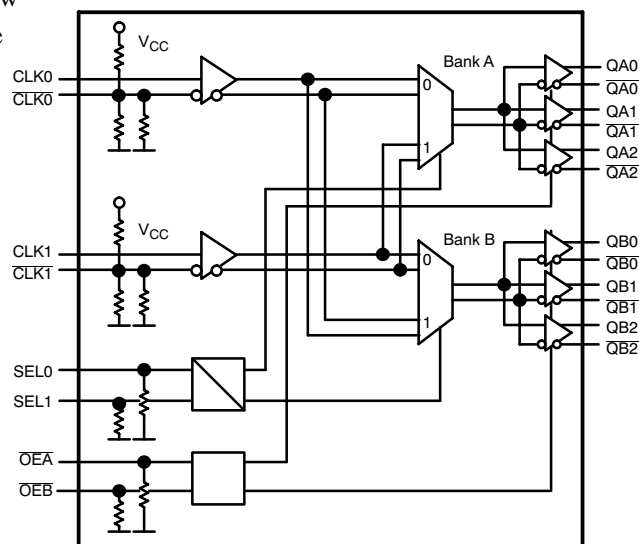


Figure 1. Functional Block Diagram

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NB4L6254

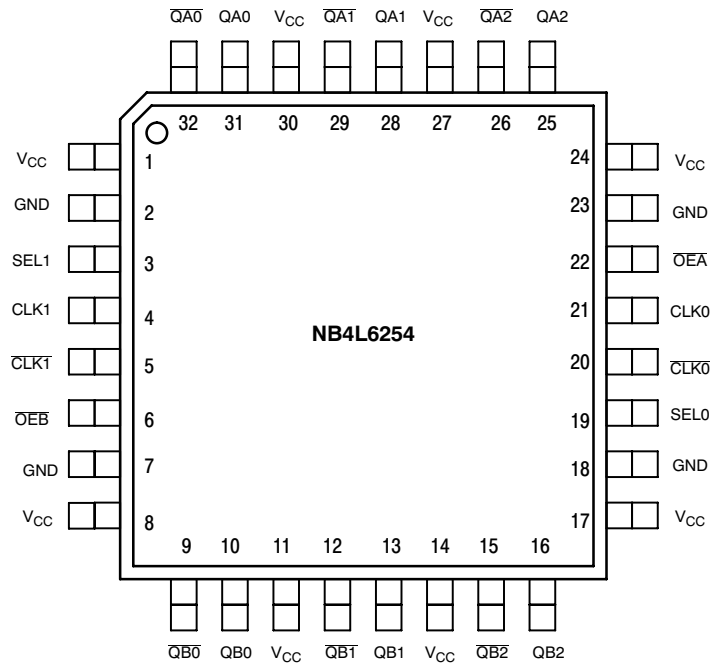


Figure 2. 32-Lead LQFP Pinout (Top View)

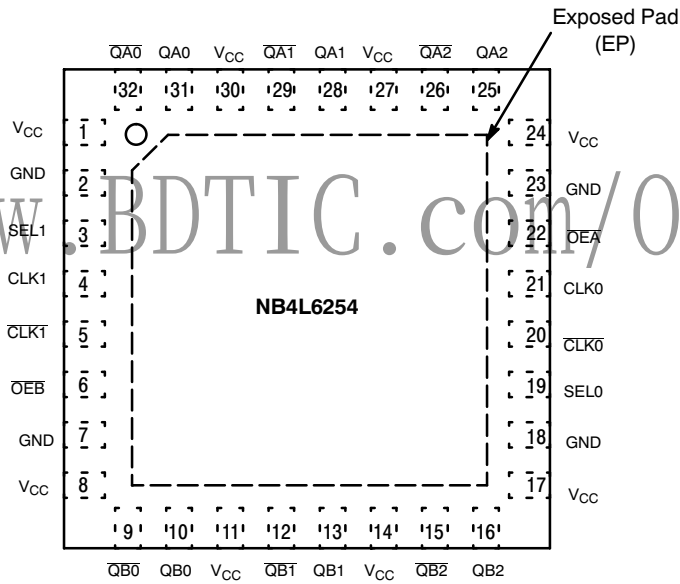


Figure 3. 32-Lead QFN Pinout (Top View)

Table 1. PIN DESCRIPTION

Pin Name	I/O	Description
CLK0, $\overline{\text{CLK0}}$	LVPECL Input	Differential reference clock signal input 0.
CLK1, $\overline{\text{CLK1}}$	LVPECL Input	Differential reference clock signal input 1.
OEAb, $\overline{\text{OEB}}$	LVC MOS Input	Output Enable
SEL0, SEL1	LVC MOS Input	Clock Switch Select
QA[0:2], $\overline{\text{QA}}[0:2]$ QB[0:2], $\overline{\text{QB}}[0:2]$	LVPECL Output	Differential LVPECL Clock Outputs, (banks A and B) Typically terminated with 50 Ω resistor to $V_{\text{CC}} - 2.0 \text{ V}$.
GND	Power Supply	Negative Supply Voltage
V_{CC}	Power Supply	Positive supply voltage. All V_{CC} pins must be connected to the positive power supply for correct DC and AC operation.
EP		The exposed pad (EP) on the QFN-32 package bottom is thermally connected to the die for improved heat transfer out of the package. The exposed pad must be attached to a heat-sinking conduit. The pad is electrically connected to GND.

Table 2. FUNCTION TABLE

Control	Default	0	1
$\overline{\text{OEA}}$	0	QA[0:2], $\overline{\text{QA}}[0:2]$ are active. Deassertion of $\overline{\text{OEA}}$ can be asynchronous to the reference clock without generation of output runt pulses	QA[0:2] = L, $\overline{\text{QA}}[0:2]$ = H (outputs disabled). Assertion of $\overline{\text{OE}}$ can be asynchronous to the reference clock without generation of output runt pulses
$\overline{\text{OEB}}$	0	QB[0:2], $\overline{\text{QB}}[0:2]$ are active. Deassertion of $\overline{\text{OEB}}$ can be asynchronous to the reference clock without generation of output runt pulses	QB[0:2] = L, $\overline{\text{QB}}[0:2]$ = H (outputs disabled). Assertion of $\overline{\text{OE}}$ can be asynchronous to the reference clock without generation of output runt pulses
SEL0, SEL1	00	Refer to Table 3	Refer to Table 3

Table 3. CLOCK SELECT CONTROL

SEL0	SEL1	CLK0 Routed To	CLK1 Routed to	Application Mode
0	0	QA[0:2] and QB[0:2]	-	1:6 Fanout of CLK0
0	1	-	QA[0:2] and QB[0:2]	1:6 Fanout of CLK1
1	0	QA[0:2]	QB[0:2]	Dual 1:3 Buffer
1	1	QB[0:2]	QA[0:2]	Dual 1:3 Buffer (Crossed)

Table 4. ATTRIBUTES

Characteristics	Value
Internal Input Pullup Resistor	37.5 k Ω
Internal Input Pulldown Resistor	75 k Ω
ESD Protection	Human Body Model Machine Model
	> 2000 V > 200 V
Latchup Immunity	>200 mA
Cin, inputs	4.0 pF (TYP)
Moisture Sensitivity (Note 1)	LQFP-32 QFN32
	Level 2 Level 1
Flammability Rating	Oxygen Index: 28 to 34
	UL 94 V-0 @ 0.125 in
Transistor Count	336
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional information, see Application Note AND8003/D.

Table 5. MAXIMUM RATINGS (Note 2)

Symbol	Parameter	Condition	Condition	Rating	Unit
V _{CC}	Positive Power Supply			-0.3 ≤ V _{CC} ≤ 3.6	V
V _{IN}	DC Input Voltage			-0.3 ≤ V _{IN} ≤ V _{CC} + 0.3	V
V _{OUT}	DC Output Voltage			-0.3 ≤ V _{OUT} ≤ V _{CC} + 0.3	V
I _{IN}	DC Input Current			± 20	mA
I _{out}	LVPECL DC Output Current	Continuous Surge		± 50 100	mA mA
T _A	Operating Temperature Range	LQFP-32		-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ _{JA}	Thermal Resistance (Junction-to-Ambient) (Note 3)	0 lfpm 500 lfpm	LQFP-32 LQFP-32	80 55	°C/W °C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	2S2P (Note 3)	LQFP-32	12 to 17	°C/W
θ _{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	QFN-32 QFN-32	31 27	°C/W °C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	2S2P	QFN-32	12	°C/W
T _{sol}	Wave Solder	Pb-Free		265	°C
V _{TT}	Output Termination Voltage			V _{CC} - 2.0, TYP	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

2. Maximum Ratings are those values beyond which device damage may occur.

3. JEDEC standard multilayer board - 2S2P (2 signal, 2 power); MIL-SPEC 883E Method 1012.1.

NB4L6254

Table 6. DC CHARACTERISTICS $V_{CC} = 2.375 \text{ V to } 3.465 \text{ V}$, $GND = 0 \text{ V}$, $T_A = -40^\circ\text{C to } +85^\circ\text{C}$

Symbol	Characteristic	Min	Typ	Max	Unit
POWER SUPPLY CURRENT					
I_{GND}	Power Supply Current (Outputs Open)		60	85	mA
LVPECL CLOCK OUTPUTS					
V_{OH}	LVPECL Output HIGH Voltage (Notes 4, 5) $V_{CC} = 3.3 \text{ V}$ $V_{CC} = 2.5 \text{ V}$	$V_{CC} - 1145$ 2155 1355	$V_{CC} - 1020$ 2280 1480	$V_{CC} - 895$ 2405 1605	mV
V_{OL}	LVPECL Output LOW Voltage (Notes 4, 5) $V_{CC} = 3.3 \text{ V}$ $V_{CC} = 2.5 \text{ V}$	$V_{CC} - 1945$ 1355 555	$V_{CC} - 1770$ 1530 730	$V_{CC} - 1600$ 1700 900	mV
CLOCK INPUTS					
V_{PP}	Dynamic Differential Input Voltage (Clock Inputs)	0.1		1.3	V
V_{CMR}	Differential Cross-point Voltage (Clock Inputs)	1.0		$V_{CC} - 0.3$	V
LVC MOS CONTROL INPUTS					
V_{IH}	Output HIGH Voltage (LVTTL/LVCMOS)	2.0			V
V_{IL}	Output LOW Voltage (LVTTL/LVCMOS)			0.8	V
I_{IH}	Input Current $V_{IN} = V_{CC}$ or $V_{IN} = GND$	-100		+100	μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- LVPECL Outputs loaded with 50Ω termination resistors to $V_{TT} = V_{CC} - 2.0 \text{ V}$ for proper operation.
- LVPECL Output parameters vary 1:1 with V_{CC} .

www.BDTIC.com/ON

NB4L6254

Table 7. AC CHARACTERISTICS $V_{CC} = 2.375\text{ V to }3.465\text{ V}$, $GND = 0\text{ V}$, $T_A = -40^\circ\text{C to }+85^\circ\text{C}$ (Note 6)

Symbol	Characteristic	Min	Typ	Max	Unit
V_{INPP}	Differential Input Voltage (Peak-to-Peak)	0.3		1.3	V
V_{CMR}	Differential Input Cross-Point Voltage (Clock Inputs)	1.2		$V_{CC} - 0.3$	V
f_{IN}	Clock Input Frequency	0		3.0	GHz
V_{OUTPP}	Differential Output Voltage Amplitude (Peak-to-Peak) (Note 7) $f_O < 1.1\text{ GHz}$ $f_O < 2.5\text{ GHz}$ $f_O < 3.0\text{ GHz}$	0.45 0.35 0.2	0.70 0.55 0.35		V
f_{CLKOUT}	Output Clock Frequency Range	0		3.0	GHz
t_{pd}	Propagation Delay $CLKx$ to Qx (Differential Configuration)	360	485	610	ps
t_{skew}	Within Device Output-to-Output Skew (Differential Configuration) Device-to-Device Skew Output Pulse Skew (Duty Cycle Skew) (Note 8)		25 30 10	50 250 60	ps
DCO	Output CLOCK Duty Cycle (DC Ref = 50%) (Note 9) $t_{REF} < 100\text{ MHz}$ $t_{REF} < 800\text{ MHz}$	49.4 45.2		50.6 54.8	%
t_{JIT}	CLOCK Random Jitter (RMS) ($SEL0 \neq SEL1$) (Note 10)		0.3	0.8	ps
t_r, t_f	Output Rise/Fall Times (Note 11) $CLKx / \overline{CLKx}$	50	130	300	ps
t_{PDL}	Output Disable Time, $T = CLK$ period	$2.5 T + t_{PD}$		$3.5 T + t_{PD}$	ns
t_{PLD}	Output Enable Time, $T = CLK$ period	$3 T + t_{PD}$		$4 T + t_{PD}$	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

6. LVPECL Outputs loaded with $50\ \Omega$ to $V_{CC} - 2.0V$.

7. $V_{OUTPP\ MIN} = 0.1\text{ V}$ @ $+85^\circ\text{C}$, $f_O < 3.0\text{ GHz}$.

8. Output Pulse Skew is the absolute difference of the propagation delay times: $|t_{PLH} - t_{PHL}|$

9. $DCO_{MIN/MAX} = 43.2\%/59.2\%$ @ $+85^\circ\text{C}$.

10. $t_{JITMAX} = 1.6\text{ ps}$ @ 85°C , 3.0 V

11. Measured 20% to 80%

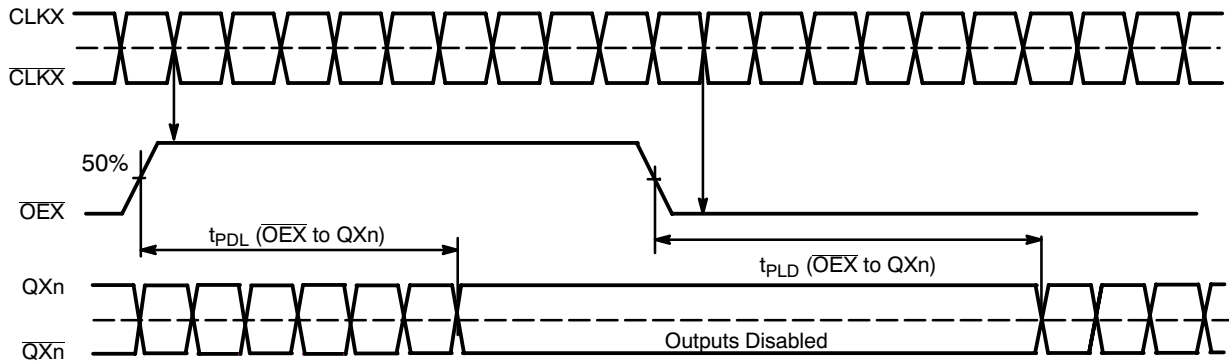


Figure 4. Output Disable / Enable Timing

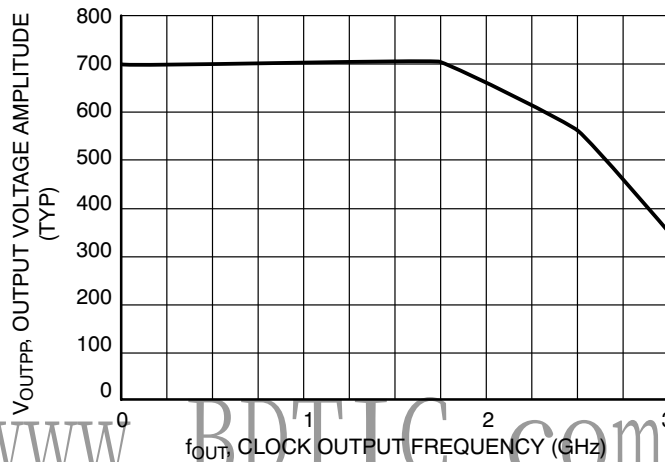


Figure 5. Output Voltage Amplitude (V_{OUTPP}) versus Clock Output Frequency at Ambient Temperature (Typical)

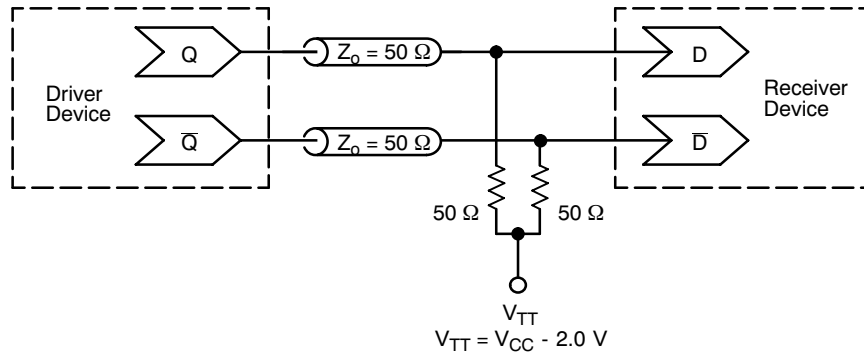


Figure 6. Typical Termination for Output Driver and Device Evaluation
(See Application Note AND8020/D - Termination of ECL Logic Devices.)

Example Configurations

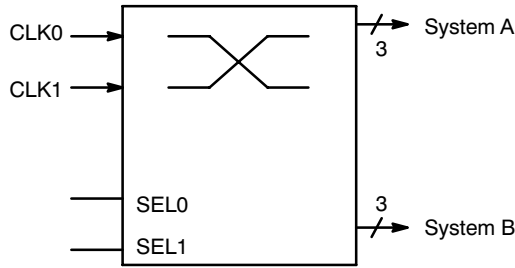


Figure 7. 2 x 2 Clock Switch

SEL0	SEL1	Switch Configuration
0	0	CLK0 Closes System A and System B
0	1	CLK1 Closes System A and System B
1	0	CLK0 Closes System A and CLK1 Closes System B
1	1	CLK1 Closes System B and CLK1 Closes System A

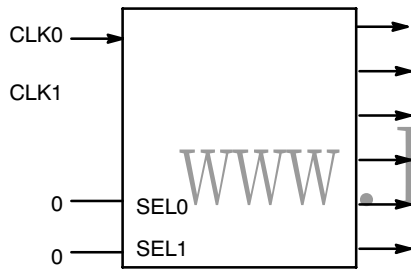


Figure 8. 1:6 Clock Fanout Buffer

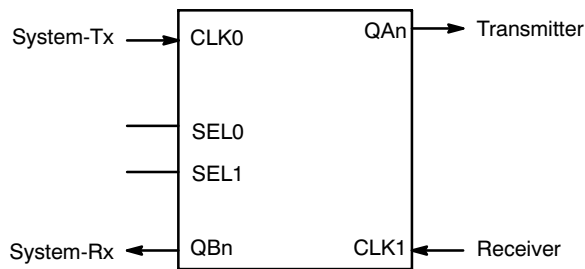


Figure 9. Loopback Device

SEL0	SEL1	Switch Configuration
0	0	System Loopback
0	1	Line Loopback
1	0	Transmit/Receive Operation
1	1	System and Line Loopback

APPLICATIONS INFORMATION

Maintaining Lowest Device Skew

The NB4L6254 guarantees low output-output bank skew at 50 ps and a part-to-part skew of 250 ps. To ensure low skew clock signals in the application, both outputs of any differential output pair need to be terminated identically, even if only one output is used. When fewer than all nine output pairs are used, identical termination of all output pairs within the output bank is recommended. If an entire output bank is not used, it is recommended to leave all of these outputs open and unterminated. This will reduce the device power consumption while maintaining minimum output skew.

Power Supply Bypassing

The NB4L6254 is a mixed analog/digital product. The differential architecture of the NB4L6254 supports low noise signal operation at high frequencies. In order to maintain its superior signal quality all V_{CC} pins should be bypassed by high-frequency ceramic capacitors connected to GND. If the spectral frequencies of the internally generated switching noise on the supply pins cross the series resonant port of an individual bypass capacitor, its overall impedance begins to look inductive and thus increases with increasing frequency. The parallel capacitor combination shown ensures that a low impedance path to ground exists for frequencies well above the noise bandwidth.

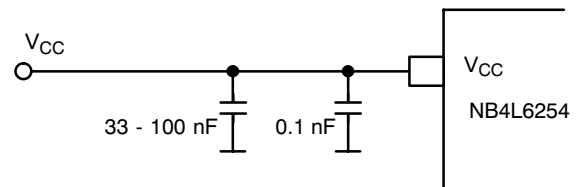


Figure 10. V_{CC} Power Supply Bypass

NB4L6254

ORDERING INFORMATION

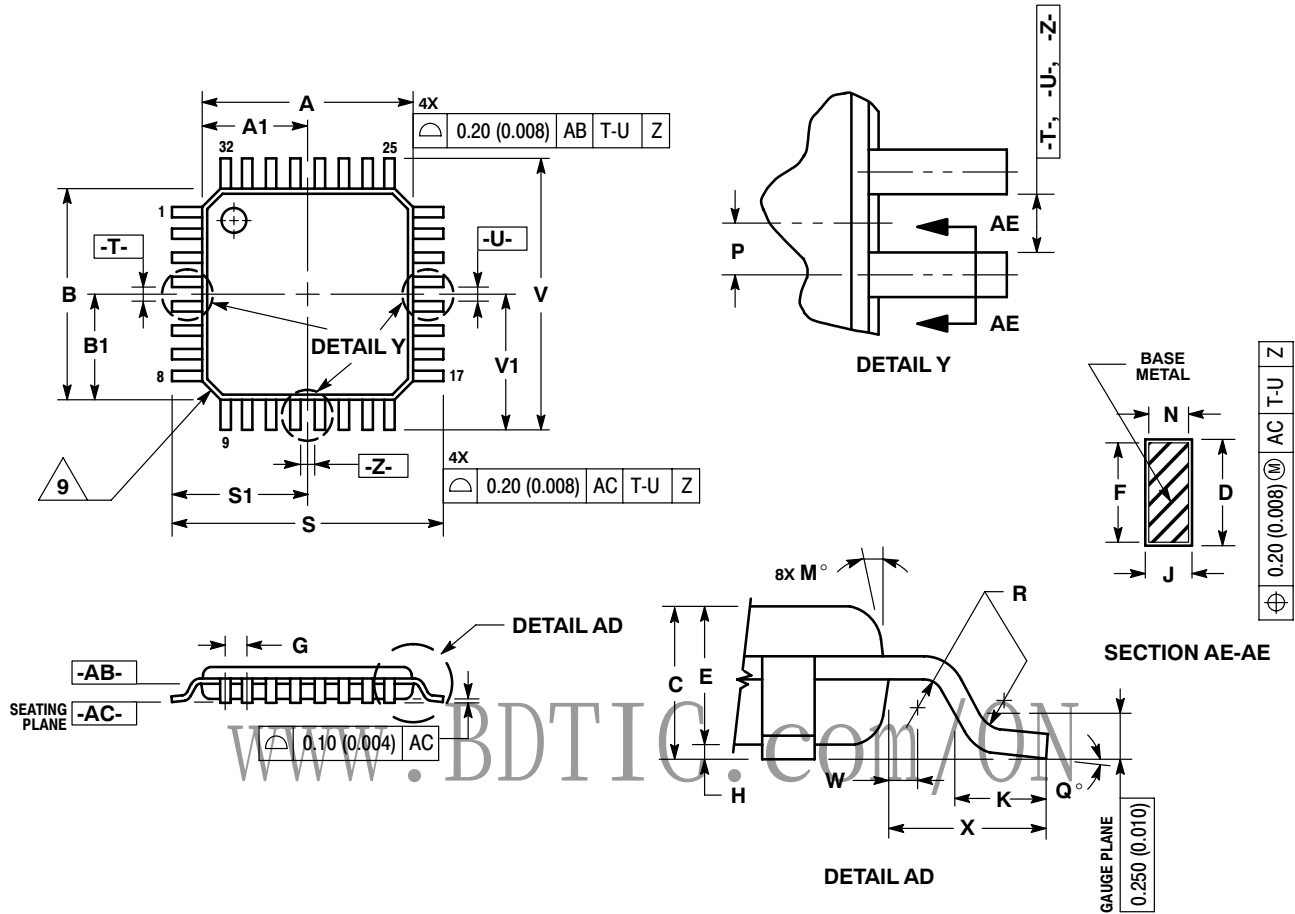
Device	Package	Shipping [†]
NB4L6254FAG	LQFP-32 (Pb-Free)	250 Units / Tray
NB4L6254FAR2G	LQFP-32 (Pb-Free)	2000 / Tape & Reel
NB4L6254MNG	QFN32 (Pb-Free)	74 Units / Rail
NB4L6254MNR4G	QFN32 (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

www.BDTIC.com/ON

PACKAGE DIMENSIONS

32 LEAD LQFP
CASE 873A-02
ISSUE C



NOTES:

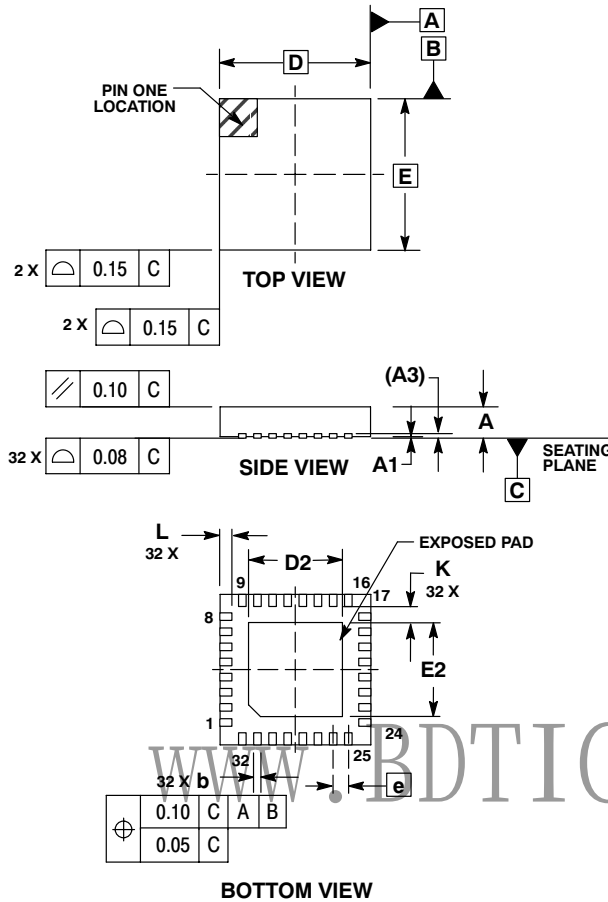
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.520 (0.020).
8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).
9. EXACT SHAPE OF EACH CORNER MAY VARY FROM DEPICTION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	7.000 BSC		0.276 BSC	
A1	3.500 BSC		0.138 BSC	
B	7.000 BSC		0.276 BSC	
B1	3.500 BSC		0.138 BSC	
C	1.400	1.600	0.055	0.063
D	0.300	0.450	0.012	0.018
E	1.350	1.450	0.053	0.057
F	0.300	0.400	0.012	0.016
G	0.800 BSC		0.031 BSC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.450	0.750	0.018	0.030
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
P	0.400 BSC		0.016 BSC	
Q	1°	5°	1°	5°
R	0.150	0.250	0.006	0.010
S	9.000 BSC		0.354 BSC	
S1	4.500 BSC		0.177 BSC	
V	9.000 BSC		0.354 BSC	
V1	4.500 BSC		0.177 BSC	
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	

NB4L6254

PACKAGE DIMENSIONS

QFN32 5*5*1 0.5 P
CASE 488AM-01
ISSUE O

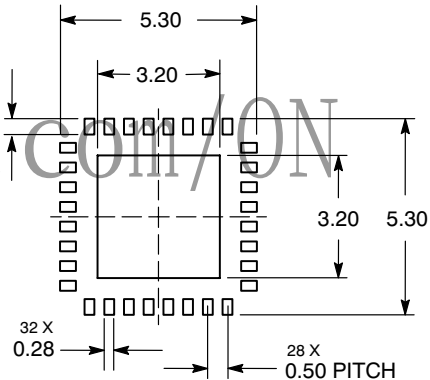


NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.800	0.900	1.000
A1	0.000	0.025	0.050
A3	0.200 REF		
b	0.180	0.250	0.300
D	5.00 BSC		
D2	2.950	3.100	3.250
E	5.00 BSC		
E2	2.950	3.100	3.250
e	0.500 BSC		
K	0.200	---	---
L	0.300	0.400	0.500

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ECLinPS is a trademark of Semiconductor Components Industries, LLC (SCILLC).

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center
2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051
Phone: 81-3-5773-3850

ON Semiconductor Website: <http://onsemi.com>

Order Literature: <http://www.onsemi.com/litorder>

For additional information, please contact your local Sales Representative.